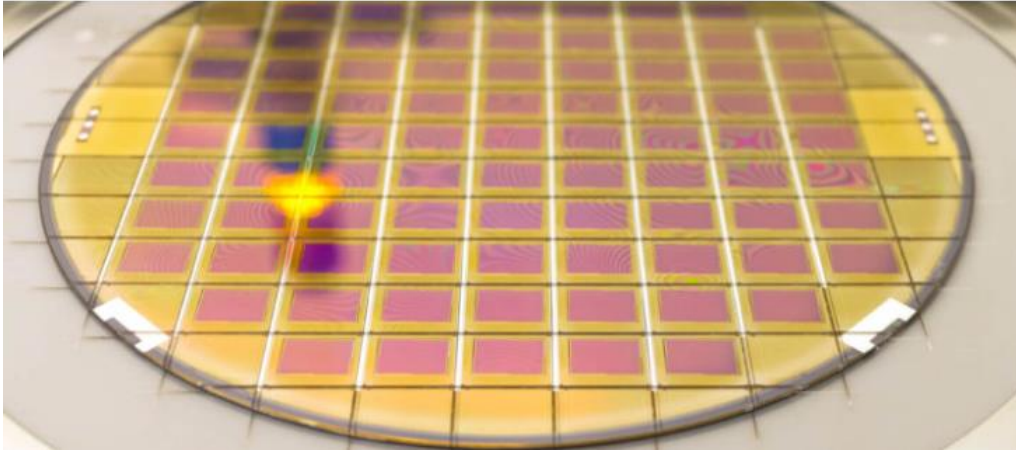


## Messplan Wafer

Abbildung Wafer (ähnlich):



Belegungsplan:

	A	B	C	D	E	F	G	H
1			Chip01	Chip02	Chip03			
2		Chip04	Chip05	Chip06	Chip07	Chip08		
3	Chip09	Chip10	Chip11	Chip12	Chip13	Chip14	Chip15	
4	Chip16	Chip17	Chip18	Chip19	Chip20	Chip21	Chip22	
5	Chip23	Chip24	Chip25	Chip26	Chip27	Chip28	Chip29	
6		Chip30	Chip31	Chip32	Chip33	Chip34		
7			Chip35	Chip36	Chip37			
8								
9								

## DATA SHEET – 6 INCH SILICON WAFER

### Orientation

Standard: (100) (111) (110)

Other possible orientations on request

Standard Tolerance:  $\pm 0.5^\circ$ , on request:  $\pm 0.02^\circ$

### OFF Cut

Compared to ON axis (100), (111), (110), (112): Up to  $14^\circ \pm 0.02^\circ$

### Type

**P-type:** Boron

**N-type:** Phosphorus, Arsenic, Antimony

**Undoped**

### Resistivity

**Cz:** from  $1\text{m}\Omega\cdot\text{cm}$  to  $150\ \Omega\cdot\text{cm}$

**FZ:** up to  $10\text{k}\ \Omega\cdot\text{cm}$

**Intrinsic:**  $> 200\ \Omega\cdot\text{cm}$

### General specifications

**Standard Diameter:** 6 inch (150mm)  $\pm 0.2\ \text{mm}$

**Standard Thickness:**  $675\ \mu\text{m} \pm 20\ \mu\text{m}$

**Standard TTV:**  $< 10\ \mu\text{m}$

**TTV min SSP:**  $10\ \mu\text{m}$

**TTV min DSP:**  $3\ \mu\text{m}$

**Minimum Thickness:**  $150\ \mu\text{m} \pm 10\ \mu\text{m}$

**Maximum Thickness:** 10 mm

**Best TTV for non-standard thickness:**  $5\ \mu\text{m}$

**Particle count:** 10 – 25

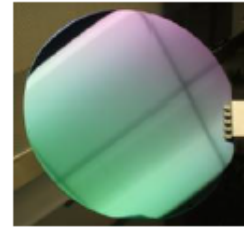
**Bow:**  $30\ \mu\text{m}$

**Roughness:** On polished surface:  $< 0.5\ \text{nm}$

**Flatness:** On polished surface:  $< 0.1\ \mu\text{m}$

### Laser marking

On Request



## DATA SHEET – 6 INCH SILICON WAFER

### Thermal Oxidation

Oxidation type	Thickness	Tolerance
Wet oxidation	200 – 3000 nm	±10 %
Standard dry oxidation	15 – 100 nm	±5 %

**Option:** Single face oxidation (photolithography)

### Single layer deposition / metallization

Layer	Method	Thickness	Tolerance
Cr, Ti, Au, Al, Pt, Mo, W Highly reflective silver coating	PVD sputtering	200 – 1000 nm Depending on metals	±10 %
Ni, Cu, Ir, Ta, Al2O3	evaporation		
Cr/Au TiW with Ti : 10% W : 90% TiW /Au with Ti : 10% W : 90% Ti/Pt	PVD		

### Multi layers deposition

On Request

Example:

